

## 3.3V TO 18V MUX with Overcurrent Limit

Check for Samples: [TPS22980](#)

### FEATURES

- Powered From 3.3V
- 4.5V to 19.8V High Voltage Switch
- 3V to 3.6V Switch
- Adjustable Current Limit
- Thermal Shutdown
- Make Before Break Switch
- High Voltage Discharge Before Low Voltage Make
- Reverse Current Blocking

### APPLICATIONS

- Notebook Computers
- Desktop Computers
- Power Management Systems

### DESCRIPTION

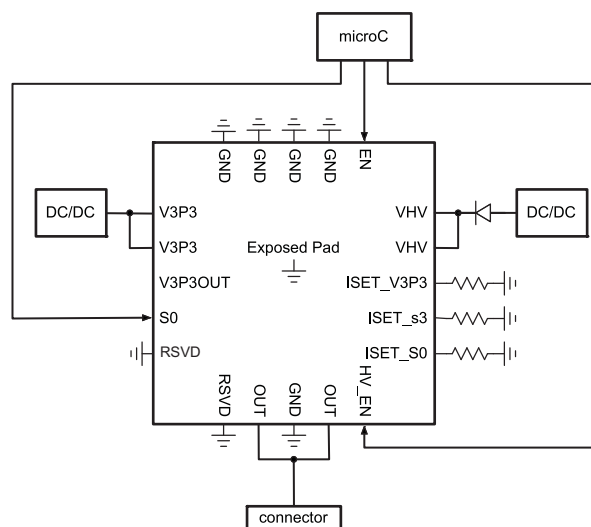
The TPS22980 is a current-limited power mux providing a connection to a peripheral device from either a low voltage supply (3.0V up to 3.6V) or a high voltage supply (5V up to 18V). The desired output is selected by digital control signals.

The high voltage (VHV) and low voltage (V3P3) switch current limits are set with external resistance. Once the current limit is reached, the TPS22980 will control the switch to maintain the current at the limit.

When the high voltage supply is not present, the TPS22980 will maintain the connection to the output from the low voltage supply. When a high voltage line and high voltage enable signal is detected by the device, the high voltage switch will be turned on in conjunction with the low voltage switch until a reverse current is detected by the low voltage switch. The low voltage switch is then disabled allowing a seamless transition from a low voltage to a high voltage supply with minimal drop and shoot-through current.

To prevent current backflow during a transition from a VHV connection to a V3P3 connection, the TPS22980 will break the VHV connection and discharge the output to approximately 3.3V. Once the output reaches 3.3V the device will connect V3P3 switch. If a load is present, the output will transition to 0V before returning to 3.3V.

The TPS22980 is available in a 4mm x 4mm x 1mm QFN package.



**Figure 1. Typical Application**



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

# TPS22980

SLVSB61B – DECEMBER 2011 – REVISED APRIL 2012

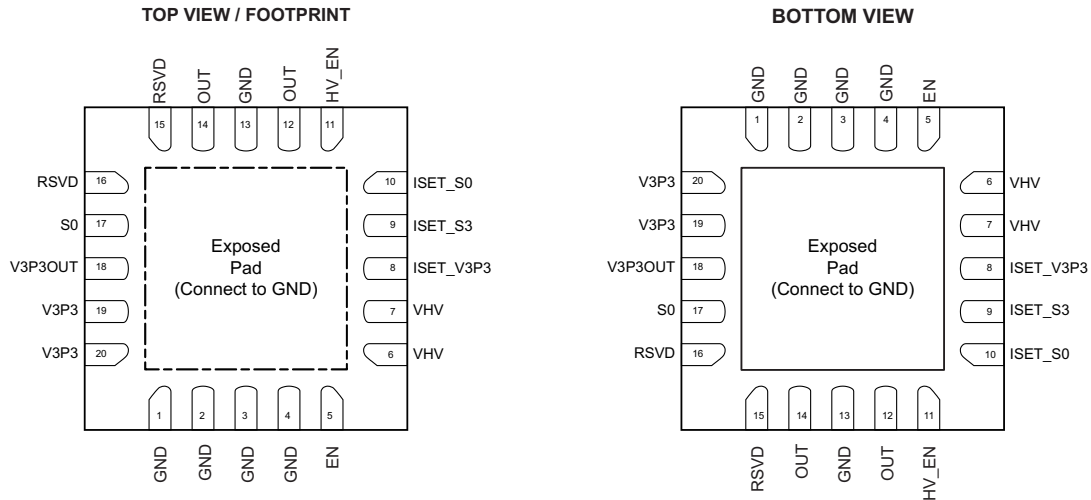
www.ti.com



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

## ORDERING INFORMATION

PART NUMBER	PACKAGE MARKING	PACKAGE	DEVICE SPECIFIC FEATURES
TPS22980RGP	PS22980	RGP	Tape and Reel



Package Size: 4mm x 4mm x 1mm height, Pad Pitch: 0.5mm

## PIN FUNCTIONS

PIN		DESCRIPTION
NO.	NAME	
1	GND	Device ground
2		
3		
4		
5	EN	Device Enable.
6	VHV	High voltage power supply input. Place a minimum of 0.1µF capacitor as close to this pin as possible.
7		
8	ISET_V3P3	Sets the current limit for V3P3. Place resistor between this pin and GND. See <a href="#">Equation 1</a> to calculate resistor value.
9	ISET_S3	Sets the current limit for VHV in S3 mode. Place resistor between this pin and GND. See <a href="#">Equation 1</a> to calculate resistor value.
10	ISET_S0	Sets the current limit for VHV in S0 mode. Place resistor between this pin and GND. See <a href="#">Equation 1</a> to calculate resistor value.
11	HV_EN	High voltage output enable.
12, 14	OUT	Power output. Place a minimum of 1µF capacitor as close to this pin as possible.
13	GND	Device ground.
15	RSVD	Reserved. Must Tie to GND.
16		
17	S0	When this pin is asserted, the device is put in S0 mode. Otherwise the device operates in S3 mode.
18	V3P3OUT	3.3V bypass output. Place a minimum of 0.1µF capacitor as close to this pin as possible.
19	V3P3	3.3V power supply input. Place a minimum of 0.1µF capacitor as close to this pin as possible.
20		
EP	GND	

## ABSOLUTE MAXIMUM RATINGS

 over operating free-air temperature range (unless otherwise noted)<sup>(1) (2)</sup>

		VALUE	UNIT
V <sub>I</sub>	Input voltage range on V3P3 (VDD) <sup>(3)</sup>	–0.3 to 3.6	V
	Input voltage range on EN, HVEN, ISET_V3P3, ISET_S0, ISET_S3, S0 <sup>(3)</sup>	–0.3 to V3P3+0.3	
	Input voltage range on VHV <sup>(3)</sup>	–0.3 to 20	
	Output voltage range at OUT <sup>(3)</sup>	–0.3 to 20	
	Output voltage range at V3P3OUT <sup>(3)</sup>	–0.3 to V3P3+0.3	
T <sub>A</sub>	Operating ambient temperature range	–40 to 85	°C
T <sub>J (MAX)</sub>	Maximum operating junction temperature	110	°C
T <sub>stg</sub>	Storage temperature range	–65 to 150	°C
ESD Rating	Charge Device Model (JESD 22 C101)	500	V
	Human Body Model (JESD 22 A114)	2	kV

- (1) Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under recommended operating conditions is not implied. Exposure to absolute–maximum–rated conditions for extended periods may affect device reliability.
- (2) In applications where high power dissipation and/or poor package thermal resistance is present, the maximum ambient temperature may have to be de-rated. Maximum ambient temperature [T<sub>A(max)</sub>] is dependent on the maximum operating junction temperature [T<sub>J(max)</sub>], the maximum power dissipation of the device in the application [P<sub>D(max)</sub>], and the junction-to-ambient thermal resistance of the part/package in the application (θ<sub>JA</sub>), as given by the following equation: T<sub>A(max)</sub> = T<sub>J(max)</sub> – (θ<sub>JA</sub> × P<sub>D(max)</sub>)
- (3) All voltage values are with respect to network ground terminal.

## THERMAL INFORMATION

THERMAL METRIC <sup>(1)</sup>		TPS22980	UNITS
		RGP	
		16 PINS	
θ <sub>JA</sub>	Junction-to-ambient thermal resistance	38.9	°C/W
θ <sub>JCtop</sub>	Junction-to-case (top) thermal resistance	30.7	
θ <sub>JB</sub>	Junction-to-board thermal resistance	11.5	
ψ <sub>JT</sub>	Junction-to-top characterization parameter	0.4	
ψ <sub>JB</sub>	Junction-to-board characterization parameter	11.4	
θ <sub>JCbot</sub>	Junction-to-case (bottom) thermal resistance	2.2	

- (1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, [SPRA953](#).

**RECOMMENDED OPERATING CONDITIONS**

			MIN	MAX	UNIT
V <sub>3P3</sub>	Supply voltage range		3.0	3.6	V
V <sub>HV</sub>			4.5	19.8	V
I <sub>LIM3P3OUT</sub>	V3P3OUT Switch current range		0	500	mA
V <sub>IH</sub>	Input logic high	EN, HV_EN, S0	V3P3-0.6	V3P3	V
V <sub>IL</sub>	Input logic low	EN, HV_EN, S0	0	0.6	V
R <sub>SET_V3P3</sub>	3.3V switch current limit set resistance		25.3	402	kΩ
R <sub>SET_S0</sub>	VHV switch current limit in S0 mode set resistance		25.3	402	kΩ
R <sub>SET_S3</sub>	VHV switch current limit in S3 mode set resistance		25.3	402	kΩ

**ELECTRICAL CHARACTERISTICS**

Unless otherwise noted the specification applies over the V<sub>DD</sub> range and operating junction temp  $-40^{\circ}\text{C} \leq T_J \leq 85^{\circ}\text{C}$ . Typical values are for V<sub>3P3</sub> = 3.3V, V<sub>HV</sub> = 15V, and T<sub>J</sub> = 25°C.

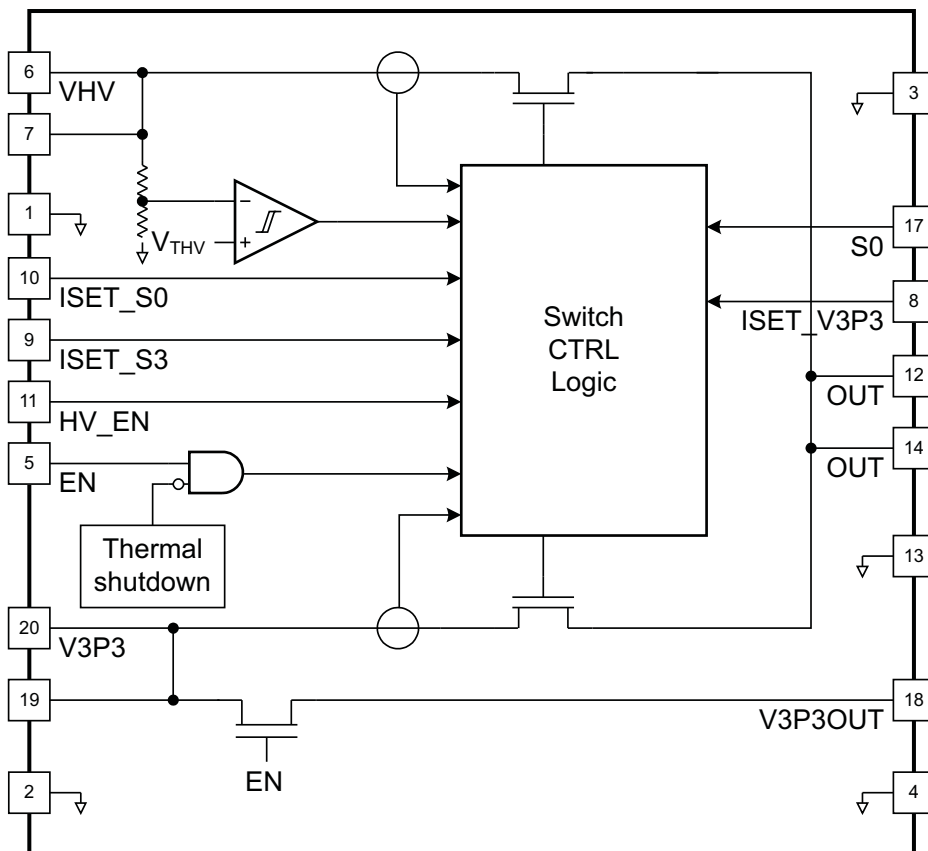
PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>POWER SUPPLIES AND CURRENTS</b>						
V <sub>3P3</sub>	V3P3 Input voltage range		3	3.3	3.6	V
V <sub>HV</sub>	VHV Input voltage range		4.5		19.8	V
I <sub>VHVACT</sub>	Active quiescent current from VHV	HV_EN = 1, EN = 1			150	μA
I <sub>VHVSD</sub>	Shutdown leakage current from VHV	HV_EN = 0, EN = 0 or 1			30	μA
I <sub>DDACT</sub>	Active quiescent current from V3P3	EN = 1, HV_EN = 0			200	μA
I <sub>DDACTHV</sub>	Active quiescent current from V3P3	EN = 1, HV_EN = 1			150	μA
I <sub>DDSD</sub>	Shutdown Quiescent Current from V3P3	EN = 0, OUT = 0V			10	μA
I <sub>DIS</sub>	OUT Discharge Current	EN = 1, V <sub>HV</sub> = 5V HV_EN = 1 → 0	5		10	mA
I <sub>IN</sub>	HV_EN, EN, S0, S3 Input pin leakage	V = 0 V			1	μA
		V = V3P3			1	μA
<b>SWITCH AND RESISTANCE CHARACTERISTICS</b>						
R <sub>SHV</sub>	VHV Switch resistance	V <sub>HV</sub> = 5 V to 18V, I <sub>VHV</sub> = 1.5 A			250	mΩ
R <sub>S3P3</sub>	V3P3 Switch resistance	V <sub>3P3</sub> = 3.3 V, I <sub>V3P3</sub> = 1.5 A			250	mΩ
R <sub>S3P3BYP</sub>	V3P3 Bypass switch resistance	V <sub>3P3</sub> = 3.3 V, I <sub>V3P3</sub> = 500 mA			500	mΩ
<b>VOLTAGE THRESHOLDS</b>						
V <sub>HVUVLO</sub>	VHV Under voltage lockout	VHV Input Falling	3.6	4		V
		VHV Input Rising		4	4.3	
V <sub>3P3UVLO</sub>	V3P3 Under voltage lockout	V3P3 Input Falling	1.8	2.25		V
		V3P3 Input Rising		2.25	2.5	
<b>THERMAL SHUTDOWN</b>						
T <sub>SD</sub>	Shutdown Temperature		110	120	130	°C
T <sub>SDHYST</sub>	Shutdown Hysteresis			10		°C

**ELECTRICAL CHARACTERISTICS (continued)**

Unless otherwise noted the specification applies over the  $V_{DD}$  range and operating junction temp  $-40^{\circ}\text{C} \leq T_J \leq 85^{\circ}\text{C}$ . Typical values are for  $V_{3P3} = 3.3\text{V}$ ,  $V_{HV} = 15\text{V}$ , and  $T_J = 25^{\circ}\text{C}$ .

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>CURRENT LIMIT</b>						
$I_{LIMHV}$	VHV Switch current limit state S0 or S3	$R_{SET\_S0,3} = 402\text{ k}\Omega$	100	110	150	mA
		$R_{SET\_S0,3} = 80.6\text{ k}\Omega$	495	525	555	
		$R_{SET\_S0,3} = 26.7\text{ k}\Omega$	1515	1575	1635	
$I_{LIM3P3}$	V3P3 Switch current limit	$R_{SET\_V3P3} = 402\text{ k}\Omega$	100	110	150	mA
		$R_{SET\_V3P3} = 80.6\text{ k}\Omega$	495	525	555	
		$R_{SET\_V3P3} = 26.7\text{ k}\Omega$	1515	1575	1635	
$I_{REV3P3}$	V3P3 Switch Reverse Current Limit		10	27	45	mA
$T_{V3P3RC}$	V3P3 Switch Reverse Current Response Time	$V_{OUT} = V_{3P3} \rightarrow V_{3P3} + 20\text{mV}$			100	$\mu\text{S}$
$T_{VHVSC}$	VHV Switch short circuit response time	$C_{OUT} = 20\text{ pF}$		8		$\mu\text{s}$
$T_{V3P3SC}$	V3P3 Switch short circuit response time	$C_{OUT} = 20\text{ pF}$		8		$\mu\text{s}$
<b>TRANSITION DELAYS</b>						
$T_{3P3OFF}$	VHV to V3P3 off time	$C_{OUT} = 1.1\mu\text{F}$ , $EN = 1$ , $HV\_EN = 1 \rightarrow 0$			6	ms
$T_{0-3.3V}$	0V to 3.3V ramp time	$C_{OUT} \leq 20\text{ pF}$			6	ms
$T_{3.3V-VHV}$	3.3V to VHV ramp time	$C_{OUT} \leq 20\text{ pF}$			6	ms
$T_{VHV-3.3V}$	VHV to 3.3V ramp time	$C_{OUT} \leq 20\text{ pF}$			23	ms
$T_{LIM}$	Overcurrent response time	$C_{OUT} \leq 20\text{ pF}$			0.5	ms

**FUNCTIONAL BLOCK DIAGRAM**



## APPLICATION INFORMATION

### CURRENT LIMIT

The TPS22980 provides current limiting in the power switches. Both the VHV supply current limit and the V3P3 supply current limit are adjustable by external resistors.

Figure 2 shows a simplified view of the TPS22980 current limit function. Both the VHV supply current limit and the V3P3 supply current limit are adjustable by external resistors.

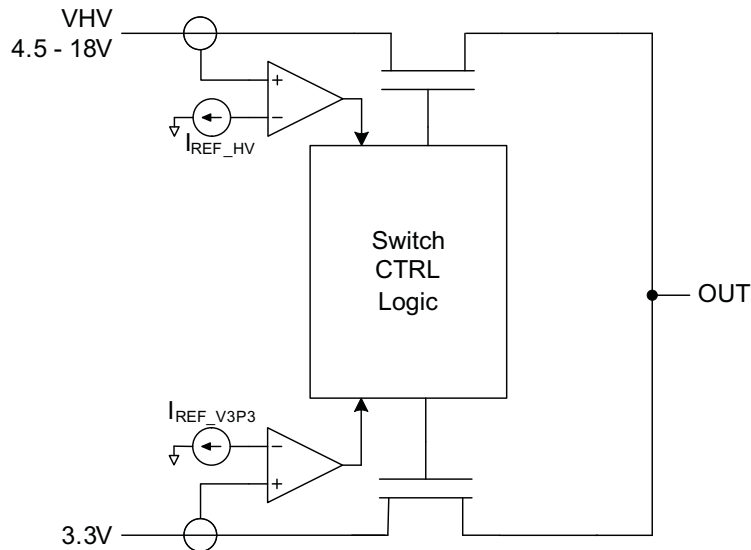


Figure 2. Simplified Current Limit Diagram

The current limit thresholds, I<sub>REF\_HV</sub> and I<sub>REF\_V3P3</sub>, are set with three external resistors as shown in Figure 3. When the TPS22980 is passes the V3P3 voltage, the current limit is set by R<sub>ISET\_V3P3</sub>. The VHV path has two modes that support two different current limits which are selected by the S0 pin. When S0 is asserted high, R<sub>ISET\_S0</sub> sets the current limit. When S0 is low, R<sub>ISET\_S3</sub> sets the current limit. This allows the system to have two separate VHV current limits for different modes such as active and sleep.

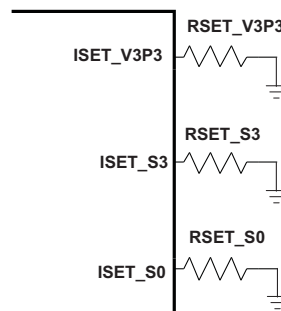


Figure 3. External R<sub>SET</sub> Resistances to Set Current Limits

## CURRENT LIMIT THRESHOLD

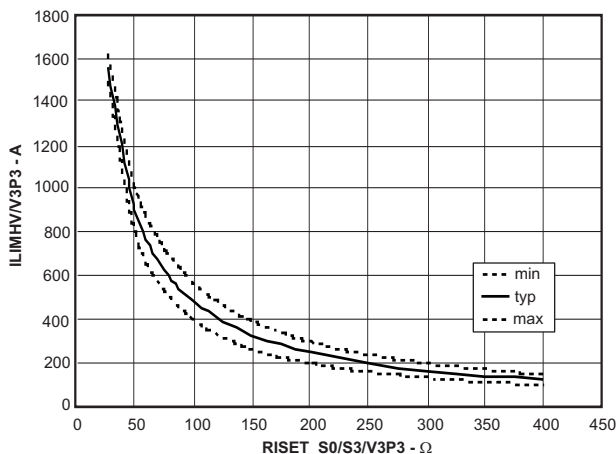


Figure 4.  $I_{LIM}$  vs  $R_{SET}$  for VHV and V3P3

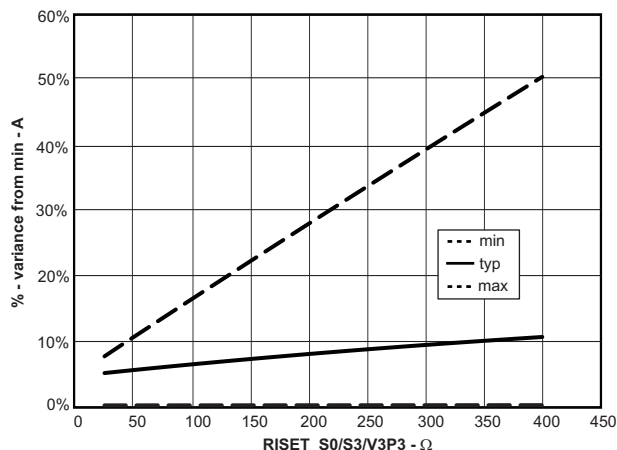


Figure 5. Percent Variance from min  $I_{LIM}$  vs  $R_{SET}$

Figure 4 shows the minimum, typical, and maximum current limit for either supply versus its corresponding  $R_{SET}$  value. Equation 1 is used to determine the  $R_{SET}$  needed to set a minimum  $I_{LIM}$  for a given supply and mode. Figure 5 shows the approximate variation from the set minimum  $I_{LIM}$  value to the typical and maximum  $I_{LIM}$  values.

$$R_{SET} = \frac{40 \text{ k}\Omega \times \text{Amps}}{I_{LIMmin}} \quad (1)$$

where:

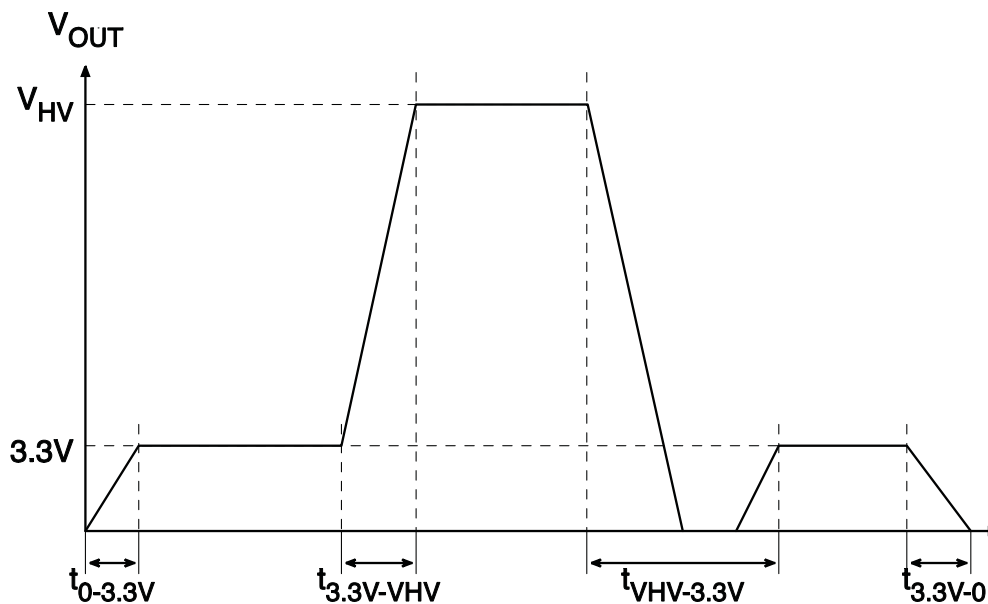
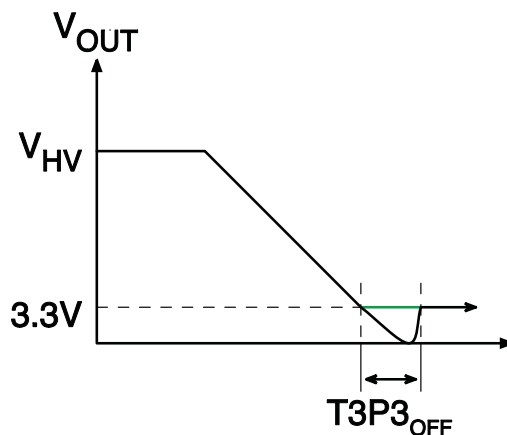
$R_{SET}$  = external resistor used to set the current limit for V3P3, VHV (S0), or VHV (S3), and

$I_{LIMmin}$  = current limit for V3P3, VHV (S0), or VHV (S3) set by the external  $R_{SET}$  resistor.

Each resistor is placed between the corresponding ISET pin and GND, as shown in Figure 3, providing a minimum current limit between 100mA and 1.5A.

## TRANSITION DELAYS

Output transitions of the TPS22980 voltages are shown in Figure 6. When the device transitions from VHV to V3P3 at the output, the power switches both turn off until the output falls to near the V3P3 voltage. During this time, a discharge current ( $I_{DIS}$ ) pulls OUT down. If a load on the line is also pulling OUT down, the output can drop to 0V due to the switch off time of T3P3OFF. Figure 7 shows the voltage drop on the output during this transition with no output capacitance.


**Figure 6. Allowable Voltage Transitions**

**Figure 7. Voltage Drop During Transitions from VHV**

## DIGITAL CONTROL SIGNALS

The voltage at OUT is controlled by two digital logic input signals, EN and HV\_EN. HV\_EN controls the state of the VHV switch and EN controls the state of V3P3 switch. [Table 1](#) lists the possible output states given the conditions of the digital logic signals.

**Table 1. Output State of OUT Given the States EN and HV\_EN**

EN	HV_EN	OUT
0	0	OPEN
0	1	OPEN
1	0	V3P3
1	1	VHV



Figure 8 shows possible combinations of EN and HV\_EN controlling OUT of the TPS22980.

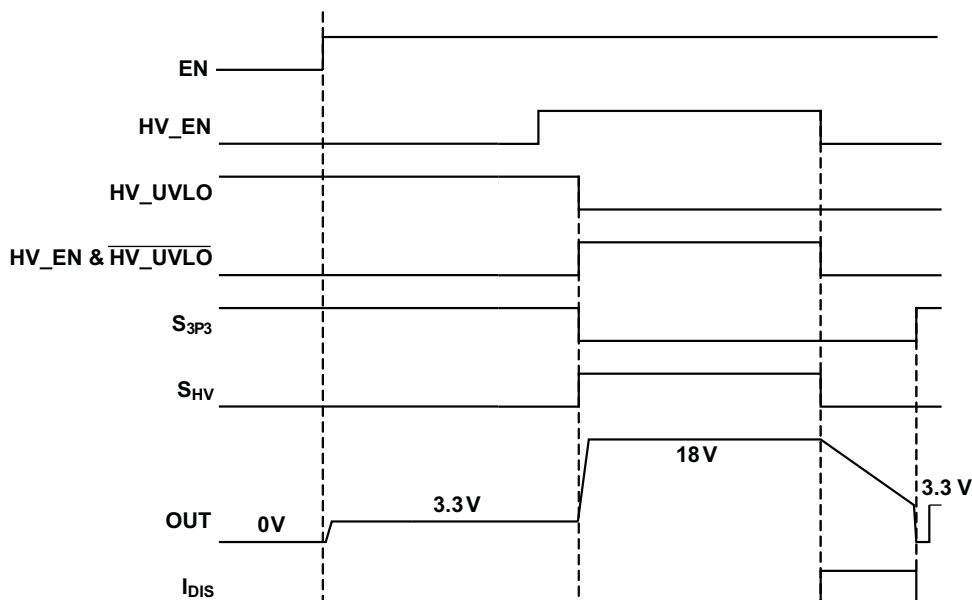


Figure 8. Logic Waveforms Displaying the Transition Between VHV and V3P3

### OVER-CURRENT LIMIT AND SHORT CIRCUIT PROTECTION

When the load at OUT attempts to draw more current than the limit set by the external RSET resistors for the V3P3 switch and VHV switch (for both S0 and S3 modes), the device will operate in a constant current mode while lowering the output voltage. Figure 9 shows the delay,  $t_{LIM}$ , which occurs when an over-current fault is detected until the output current is lowered to  $ILIMHV$  tolerances for VHV or  $ILIM3V3$  tolerances for V3P3 as shown in Figure 4.

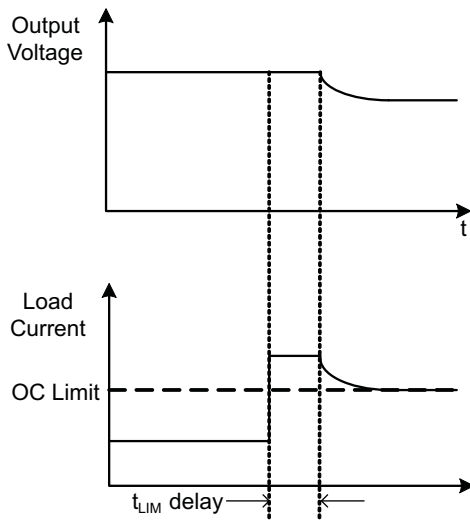


Figure 9. Overcurrent Output Response

All short circuit conditions are treated as over-current conditions. In the event of a short circuit, the device will limit the output current to the corresponding  $R_{SET}$  value and continue to do so until thermal shutdown is encountered or the short circuit condition is removed.

# TPS22980

SLVSB61B – DECEMBER 2011 – REVISED APRIL 2012

www.ti.com

## Reverse Current Protection

Reverse current protection for the V3P3 supply to OUT triggers at  $I_{REV3P3}$  causing the V3P3 supply switch to open. When the HV\_EN signal is not asserted and reverse current protection is triggered, a discharge current source is turned on to bring the output voltage to 3.3V nominal.

## Thermal Shutdown

The device enters thermal shutdown when junction temperature reaches  $T_{SD}$ . The device will resume the previous state on power up once the junction temperature has dropped by  $10^{\circ}\text{C}$ . Connect thermal vias to the exposed GND pad underneath the device package for improved thermal diffusion.

## UVLO

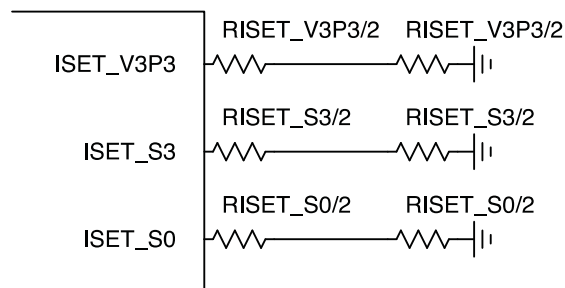
When the VHV rail reaches the under-voltage lockout threshold of  $V_{HVUVLO}$  while HV\_EN is high, the device will switch back to V3P3. Once the UVLO condition has cleared, the device will switch to VHV again. When the V3P3 rail reaches the under-voltage lockout threshold of  $V_{3P3UVLO}$ , regardless of the states of any digital logic controls, the device will open all switches and enter a reset condition.

## Input Inductive Bounce at Short Circuit

When the TPS22980 is operating at high currents and high input voltage on VHV, a short circuit condition can cause the input to exceed the maximum safe operating condition for VHV. When a significant inductance is present at the VHV input, sudden turn off of current through the device may produce a large enough inductive voltage bounce that exceeds the maximum safe operating condition and may damage the TPS22980. To prevent this, reduce any inductance at the input. Input capacitors, such as  $4.7\mu\text{F}$ , can reduce the supply bounce and are recommended.

## Single Point Failure Protection

The TPS22980 current limits are set by the R<sub>ISET</sub> resistances. Shorting one of these resistance would result in a single point failure that removes the current limiter for that particular input and mode. Without current limiting, an excessive current load may damage the TPS22980 and the system. To prevent a single point failure from occurring, the R<sub>ISET</sub> resistances can be divided into two series resistances each as shown in [Figure 10](#). Failure of a single resistance will not result in runaway current and damage.



**Figure 10. R<sub>ISET</sub> Division to Prevent Single Point Failure**

## REVISION HISTORY

---

**Changes from Original (December 2011) to Revision A** **Page**

- Changed Typical Application figure. .... 1
  - Added bottom view pin out information. .... 2
  - Updated Pin Functions Table. .... 2
  - Added reverse current and thermal shutdown parameters to the ELECTRICAL CHARACTERISTICS table. .... 4
  - Updated the APPLICATION INFORMATION section. .... 6
- 

**Changes from Revision A (February 2012) to Revision B** **Page**

- Changed bottom view pin out information. .... 2
-

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
TPS22980RGPR	ACTIVE	QFN	RGP	20	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

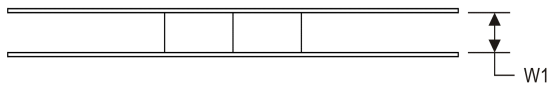
<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

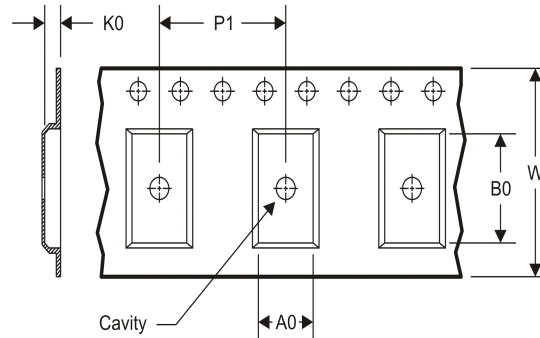
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**TAPE AND REEL INFORMATION**

**REEL DIMENSIONS**



**TAPE DIMENSIONS**



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS22980RGPR	QFN	RGP	20	3000	330.0	12.4	4.25	4.25	1.15	8.0	12.0	Q2

**TAPE AND REEL BOX DIMENSIONS**

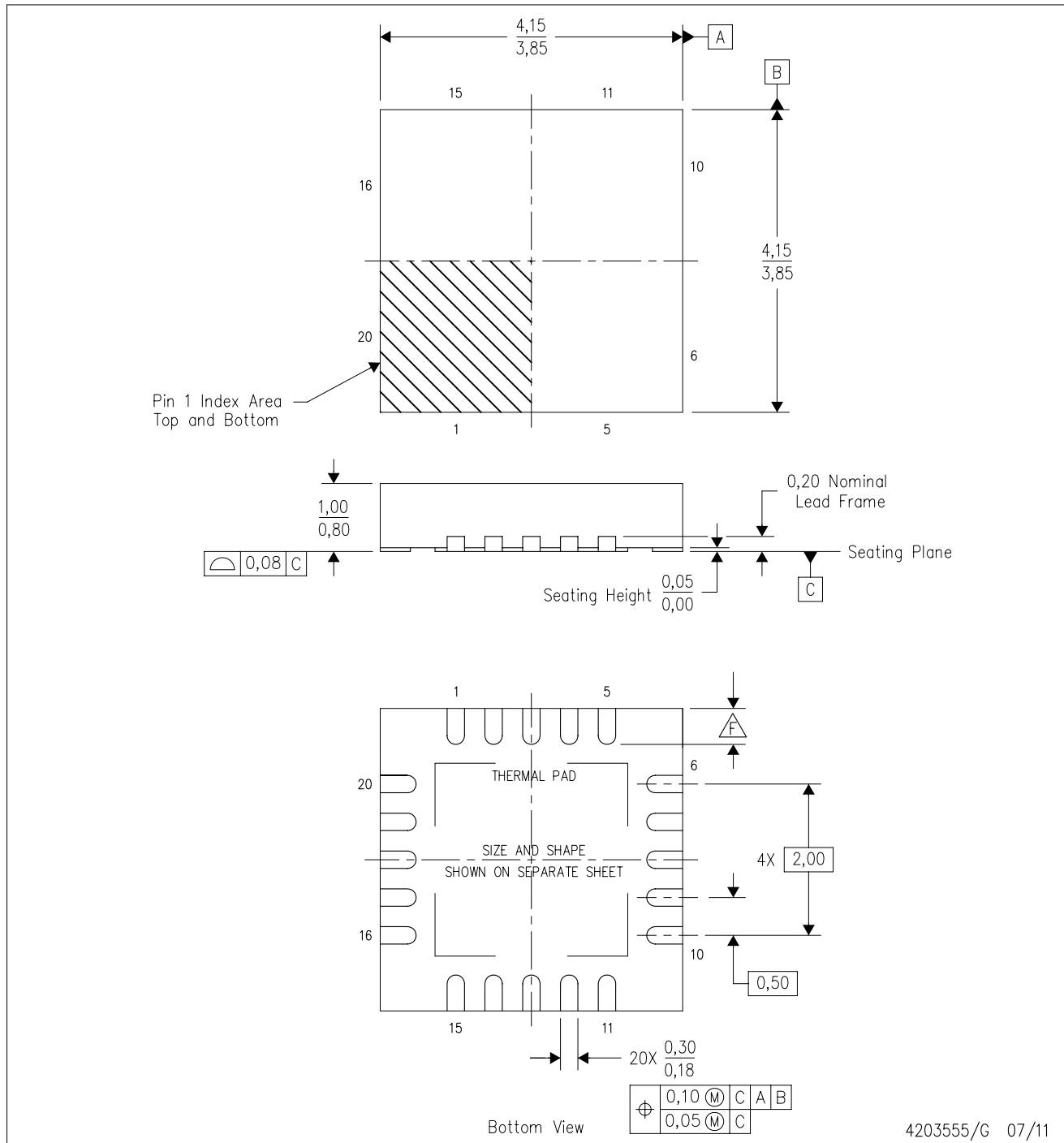


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS22980RGPR	QFN	RGP	20	3000	367.0	367.0	35.0

RGP (S-PVQFN-N20)

PLASTIC QUAD FLATPACK NO-LEAD



- NOTES:
- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - This drawing is subject to change without notice.
  - QFN (Quad Flatpack No-Lead) package configuration.
  - The package thermal pad must be soldered to the board for thermal and mechanical performance.
  - See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
- Check thermal pad mechanical drawing in the product datasheet for nominal lead length dimensions.

## THERMAL PAD MECHANICAL DATA

RGP (S-PVQFN-N20)

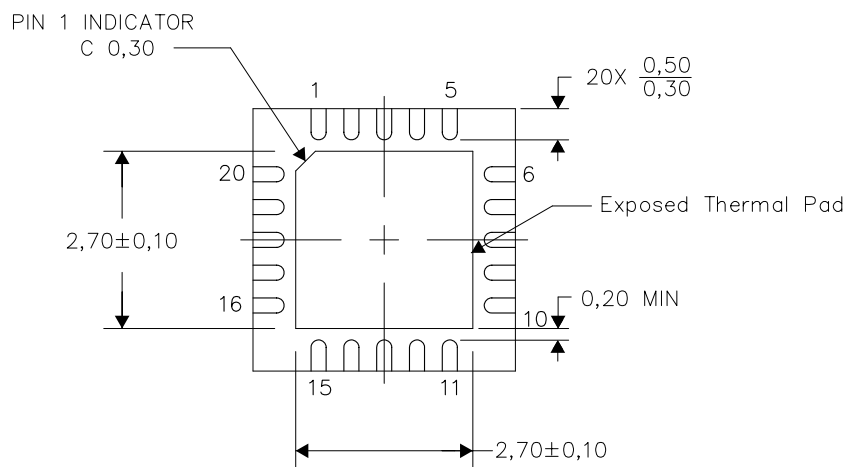
PLASTIC QUAD FLATPACK NO-LEAD

### THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at [www.ti.com](http://www.ti.com).

The exposed thermal pad dimensions for this package are shown in the following illustration.



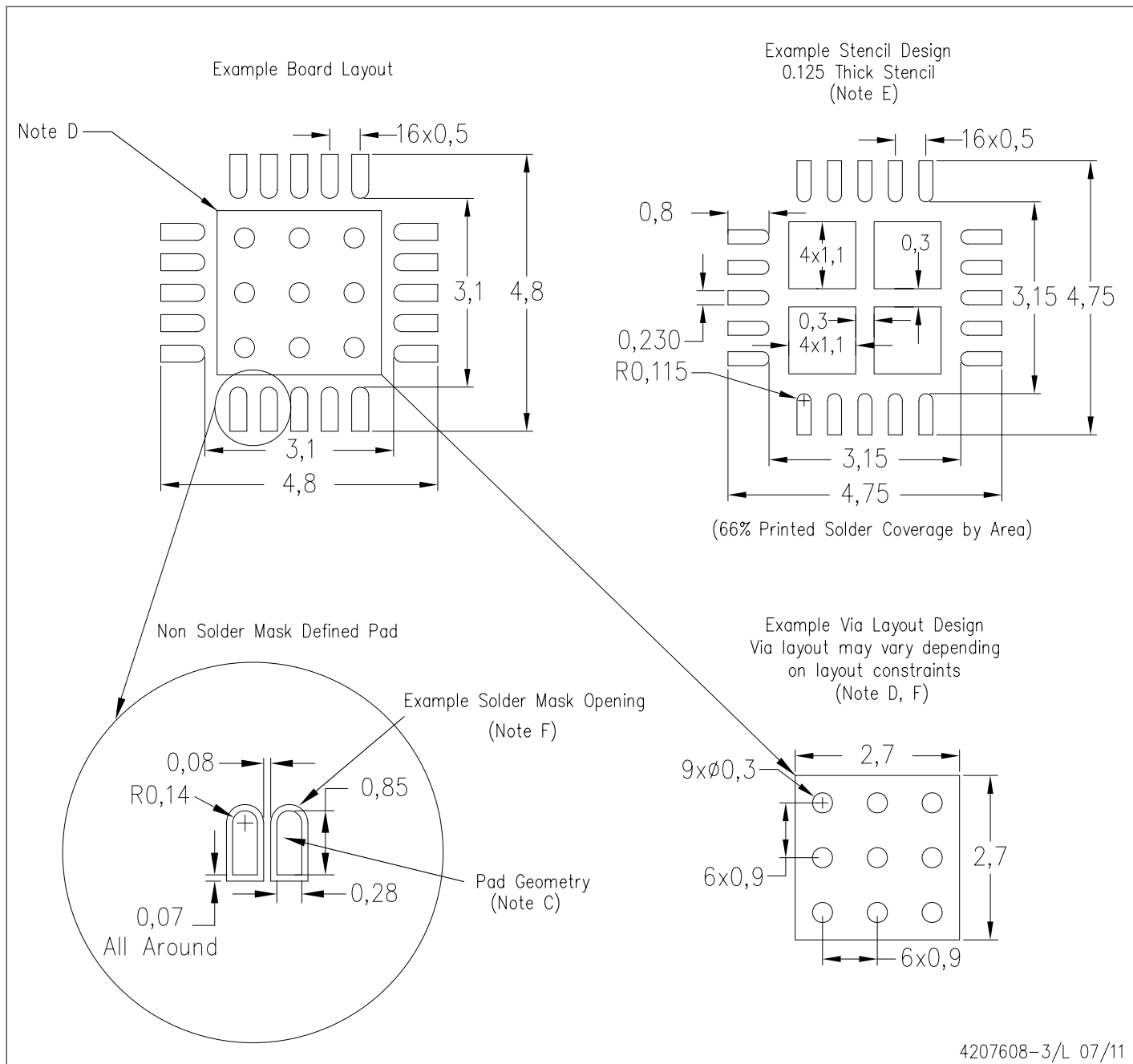
Bottom View

Exposed Thermal Pad Dimensions

4206346-3/X 02/12

NOTES: A. All linear dimensions are in millimeters





- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat-Pack Packages, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at [www.ti.com](http://www.ti.com) <<http://www.ti.com>>.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
  - Customers should contact their board fabrication site for recommended solder mask tolerances and via tenting recommendations for vias placed in the thermal pad.

## IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46C and to discontinue any product or service per JESD48B. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components which meet ISO/TS16949 requirements, mainly for automotive use. Components which have not been so designated are neither designed nor intended for automotive use; and TI will not be responsible for any failure of such components to meet such requirements.

### Products

Audio	<a href="http://www.ti.com/audio">www.ti.com/audio</a>
Amplifiers	<a href="http://amplifier.ti.com">amplifier.ti.com</a>
Data Converters	<a href="http://dataconverter.ti.com">dataconverter.ti.com</a>
DLP® Products	<a href="http://www.dlp.com">www.dlp.com</a>
DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>
Clocks and Timers	<a href="http://www.ti.com/clocks">www.ti.com/clocks</a>
Interface	<a href="http://interface.ti.com">interface.ti.com</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>
Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>
Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>
RFID	<a href="http://www.ti-rfid.com">www.ti-rfid.com</a>
OMAP Mobile Processors	<a href="http://www.ti.com/omap">www.ti.com/omap</a>
Wireless Connectivity	<a href="http://www.ti.com/wirelessconnectivity">www.ti.com/wirelessconnectivity</a>

### Applications

Automotive and Transportation	<a href="http://www.ti.com/automotive">www.ti.com/automotive</a>
Communications and Telecom	<a href="http://www.ti.com/communications">www.ti.com/communications</a>
Computers and Peripherals	<a href="http://www.ti.com/computers">www.ti.com/computers</a>
Consumer Electronics	<a href="http://www.ti.com/consumer-apps">www.ti.com/consumer-apps</a>
Energy and Lighting	<a href="http://www.ti.com/energy">www.ti.com/energy</a>
Industrial	<a href="http://www.ti.com/industrial">www.ti.com/industrial</a>
Medical	<a href="http://www.ti.com/medical">www.ti.com/medical</a>
Security	<a href="http://www.ti.com/security">www.ti.com/security</a>
Space, Avionics and Defense	<a href="http://www.ti.com/space-avionics-defense">www.ti.com/space-avionics-defense</a>
Video and Imaging	<a href="http://www.ti.com/video">www.ti.com/video</a>

**TI E2E Community** [e2e.ti.com](http://e2e.ti.com)



## Стандарт Электрон Связь

Мы молодая и активно развивающаяся компания в области поставок электронных компонентов. Мы поставляем электронные компоненты отечественного и импортного производства напрямую от производителей и с крупнейших складов мира.

Благодаря сотрудничеству с мировыми поставщиками мы осуществляем комплексные и плановые поставки широчайшего спектра электронных компонентов.

Собственная эффективная логистика и склад в обеспечивает надежную поставку продукции в точно указанные сроки по всей России.

Мы осуществляем техническую поддержку нашим клиентам и предпродажную проверку качества продукции. На все поставляемые продукты мы предоставляем гарантию .

Осуществляем поставки продукции под контролем ВП МО РФ на предприятия военно-промышленного комплекса России , а также работаем в рамках 275 ФЗ с открытием отдельных счетов в уполномоченном банке. Система менеджмента качества компании соответствует требованиям ГОСТ ISO 9001.

Минимальные сроки поставки, гибкие цены, неограниченный ассортимент и индивидуальный подход к клиентам являются основой для выстраивания долгосрочного и эффективного сотрудничества с предприятиями радиоэлектронной промышленности, предприятиями ВПК и научно-исследовательскими институтами России.

С нами вы становитесь еще успешнее!

### Наши контакты:

**Телефон:** +7 812 627 14 35

**Электронная почта:** [sales@st-electron.ru](mailto:sales@st-electron.ru)

**Адрес:** 198099, Санкт-Петербург,  
Промышленная ул, дом № 19, литера Н,  
помещение 100-Н Офис 331